

	Type	L #	Hits	Search Text	DBs	Time Stamp
1	BRS	L1	173	(substrate or substrates or wafer or wafers) and (polyphenylene adj3 polyimide)	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2002/10/24 08:15
2	BRS	L2	9	1 and (transistor or transistors)	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2002/10/24 08:17
3	BRS	L3	1	polyimide same (biphenyl adj3 tetracarboxylic adj3 acid adj8 alkanediamine)	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2002/10/24 08:31
4	BRS	L4	20	(substrate or substrates) adj10 (polyphenylene adj3 polyimide)	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2002/10/24 08:37
5	BRS	L5	91789	(substrate or substrates) adj10 (passivating or passivation or insulator or insulating)	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2002/10/24 08:38

	Type	L #	Hits	Search Text	DBs	Time Stamp
6	BRS	L6	31047	5 and (transistor or transistors)	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2002/10/24 08:39
7	BRS	L7	145	6 and (polyphenylene)	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2002/10/24 08:39
8	BRS	L8	107	7 and polyimide	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2002/10/24 08:39
9	BRS	L10	1	9 and tetracarboxylic	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2002/10/24 08:39
10	BRS	L9	13	8 and biphenyl	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2002/10/24 08:40

CLIPPEDIMAGE= JP407090244A

PAT-NO: JP407090244A

DOCUMENT-IDENTIFIER: JP 07090244 A

TITLE: ELECTRICALLY CONDUCTIVE ADHESIVE SHEET

PUBN-DATE: April 4, 1995

INVENTOR-INFORMATION:

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N/A

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;C09J121/00 ;H01B001/22 ;H01L021/52

ABSTRACT:

PURPOSE: To obtain the sheet excellent in resistance to moisture and hydrolysis, causing no warpage or cracking of semiconductor chips applied therewith, by releasably setting on a substrate film an adhesive essentially comprising each specific polyimide resin and high-molecular weight rubber and electrically conductive powder.

CONSTITUTION: The objective electrically conductive adhesive sheet can be obtained by setting on a substrate film an adhesive essentially comprising (A) a polyimide resin of formula I [R<SP>1</SP> is tetravalent organic acid residue, a biphenyl ether tetracarboxylic acid of formula II accounts for

≥50mol% of the total acid components constituting
R<SP>1</SP>; R<SP>2</SP>
is divalent diamine residue, a diamine compound of formula
III (X is
CH<SB>2</SB>, O, etc.) accounts for 50-99mol% of the total
diamine components
constituting R<SP>2</SP> and a diaminosiloxane of formula
IV (R<SP>3</SP> and
R<SP>4</SP> are each divalent organic group;
R<SP>5</SP>-R<SP>8</SP> are each
1-6C hydrocarbon; n is 0-12) 50-1mol%], (B) a
high-molecular weight rubber
≥10000 in weight- average molecular weight and (C)
electrically conductive
powder.

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